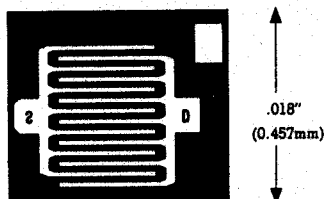


CHIP NUMBER
FN7.1



.023"
(0.584mm)

Die Size: 18 x 23 (mils)
0.457 x .0584(mm)
3 x 3 (mils)
Pad Size: 0.076 x 0.076(mm)
GATE-SUBSTRATE

CONTACT METALLIZATION

Top Contact: > 12,000
Å Aluminum

Backside Contact: 3,000 Å Gold

ASSEMBLY RECOMMENDATIONS

It is advisable that:

- the die be eutectically mounted with gold silicon preform 98/2%.
- 1 mil (0.0254mm) aluminum wire be ultrasonically attached to the top contact.

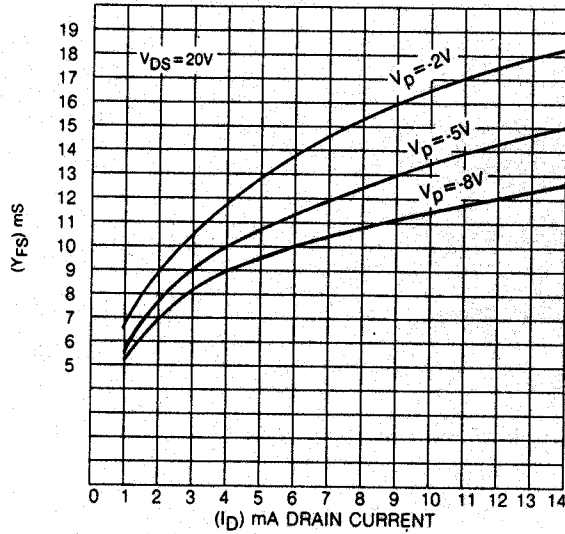
TYPICAL ELECTRICAL CHARACTERISTICS

PARAMETER	MIN.	TYP	MAX.	UNIT	TEST CONDITIONS
BV_{GSS}	-30	-50	-70	V	$V_{DS} = 0, I_G = 1\mu A$
I_{DSS}	5.0	60	150	mA	$V_{DS} = 20V, V_{GS} = 0$
g_{fs}		8		mmho	$V_{DS} = 20V, I_D = 2mA$
I_{GSS}		-20	-200	pA	$V_{GS} = -20V, V_{DS} = 0$
r_{DS}	20	40	100	Ω	$V_{DS} = 100mV, V_{GS} = 0$
$V_{GS(off)}$	-0.5	-4.5	-10	V	$V_{DS} = 20V, I_D = 1nA$
C_{rss}	3.0	3.5	4.0	pF	$V_{DS} = 15V, I_D = 5mA, f = 1MHz$
C_{iss}	10	12	16	pF	$V_{DS} = 15V, I_D = 5mA, f = 1MHz$
$\bar{e}_n$		7		nV/ $\sqrt{Hz}$	$V_{DS} = 15V, I_D = 5mA, f = 1KHz$

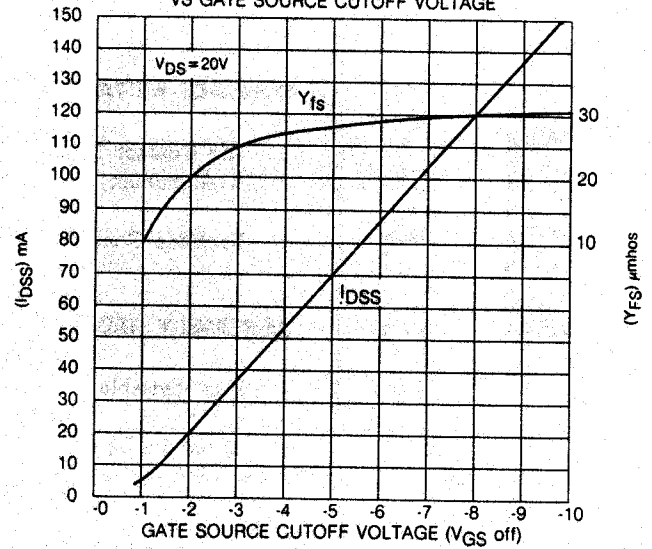
TYPICAL DEVICE TYPES: 2N4091 - 2N4093, 2N4391 - 2N4393, 2N4856 - 2N4861, KK4391 - KK4393

CHIP TYPE FN7.1

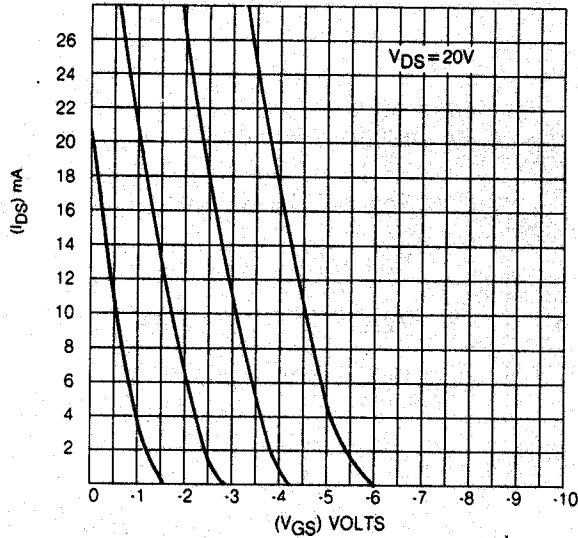
FORWARD TRANSADMITTANCE



SHORT CIRCUIT FORWARD TRANSADMITTANCE
VS GATE SOURCE CUTOFF VOLTAGE



TRANSFER CHARACTERISTICS



COMMON SOURCE DRAIN CHARACTERISTICS

